



IEEE International Conference on Multimedia & Expo (ICME) has been the flagship multimedia conference sponsored by four IEEE societies (Communications, Computer, Circuits and Systems; and Signal Processing) since 2000. It serves as a forum to promote the exchange of the latest advances in multimedia technologies, systems and applications from both the research and development perspectives of the circuits and systems, communications, computer and signal processing communities, among others. An Exposition of multimedia products, animations and industries will be held in conjunction with the conference.

The goal of the **Exhibit and Industrial Program** is to promote applied research and applications, as well as facilitate collaborations between industrial and academia members of the multimedia community.

Application for Exhibition Opportunities

Company Name: _____

Address: _____ City: _____ State: _____

Postal Code: _____ Country: _____ Phone: _____

Company website: _____ Email: _____

Contact Name & Title: _____

Company Information/Product Description: _____

*Note that the **exhibit registration includes** space (3x2m²), Internet access, electricity and a laptop (if needed). It also includes one free conference registration as well.*

Industry Exhibitor

875 EUR

Book Publisher

300 EUR

Exhibitor Badges

Exhibitor 1:

Name: _____ Title: _____

Exhibitor 2:

Name: _____ Title: _____

Exhibitor 3:

Name: _____ Title: _____

Payment Information

Payment in full must be submitted with this application. Payment can be made via checks or credit card. Checks should be made payable to IEEE ICME 2011. For credit card payment, please fill out the following:

Credit card type: __ Visa __ MasterCard __ American Express

Credit Card Number: _____ Expiration Date (MM/YYYY): _____

Name on Card: _____

Amount to Charge (€): _____

Billing Address 1: _____

Billing Address 2: _____

City: _____ State/Zip code: _____ Country: _____ Signature: _____

If interested

Please contact with the Exhibition & Events Chairs:

Oscar Garcia-Panella, Ramon Llull University-La Salle, Spain (oscarq@salle.url.edu)

Tom Malzbender, HP Labs, USA (tom.malzbender@hp.com)